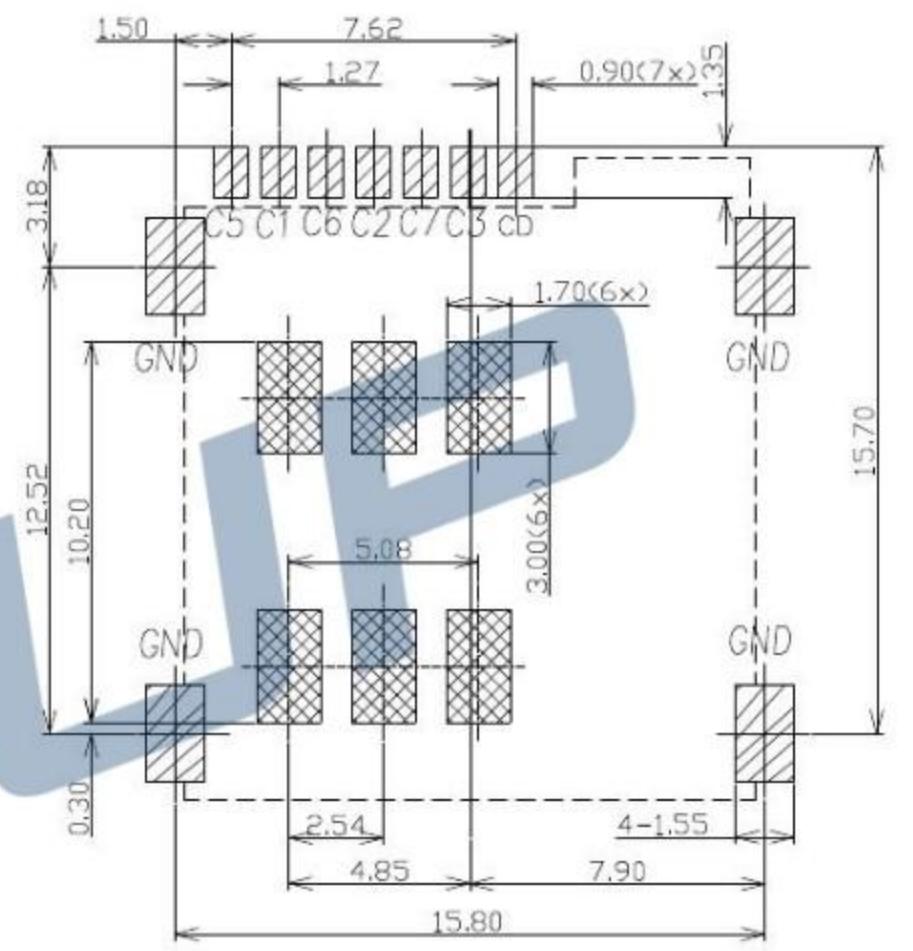
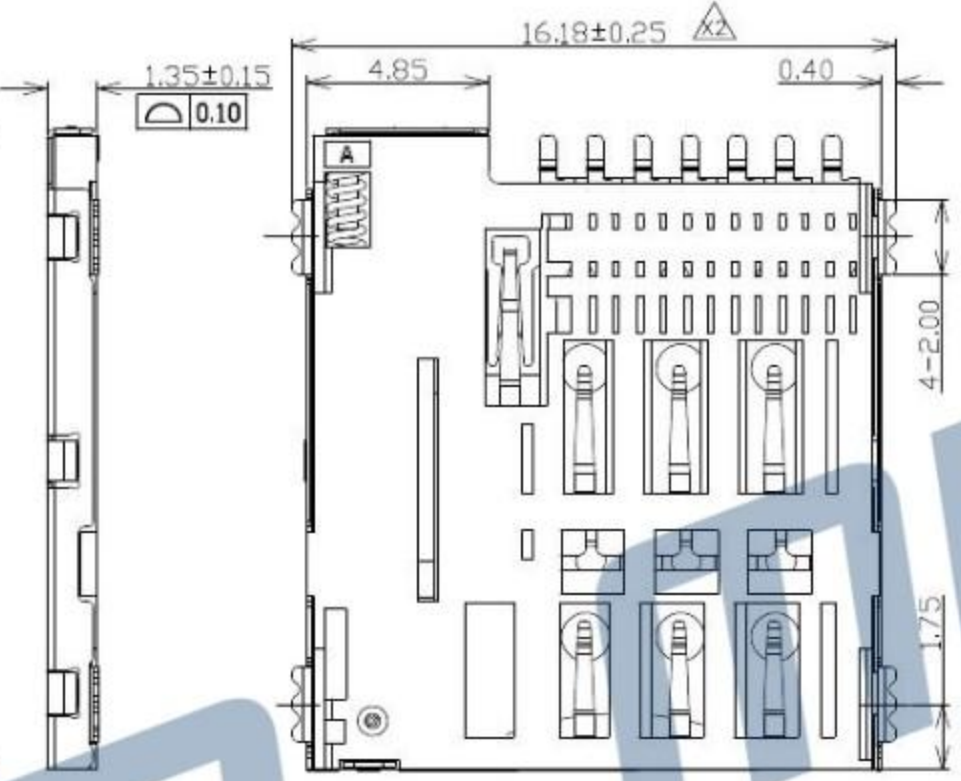
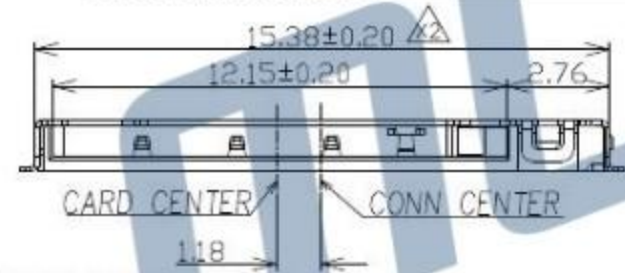
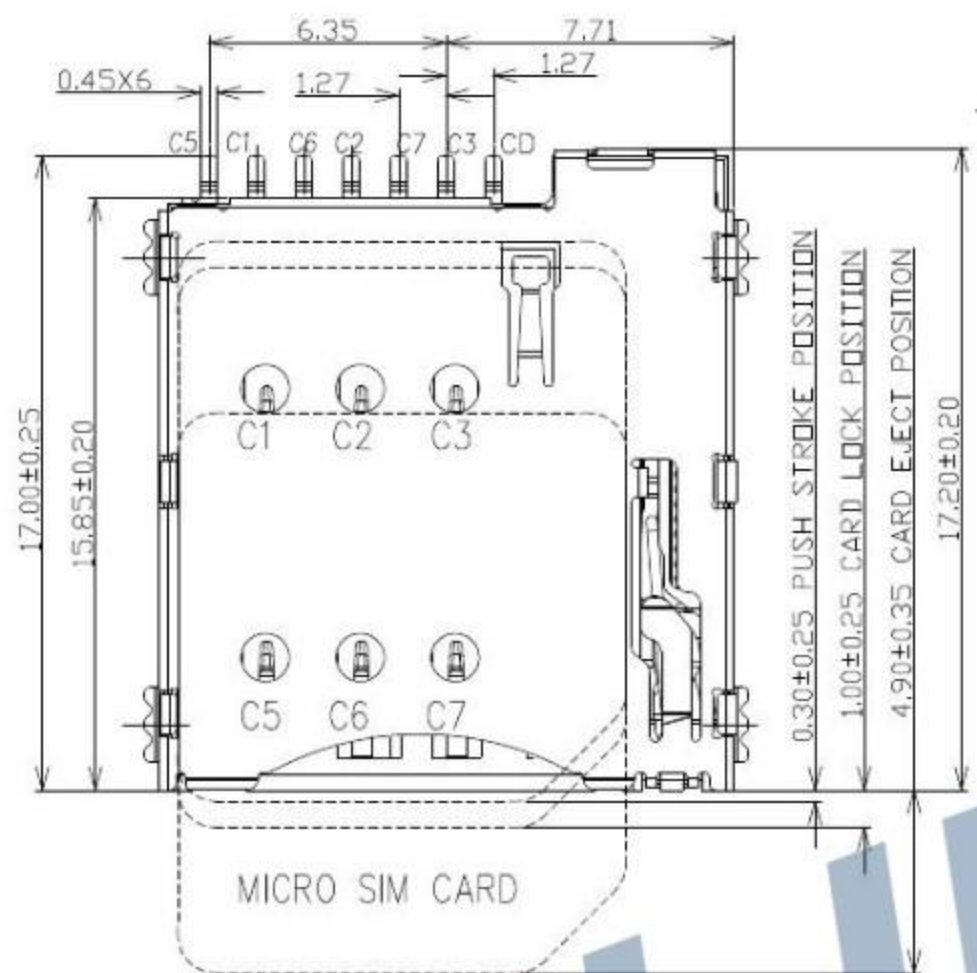


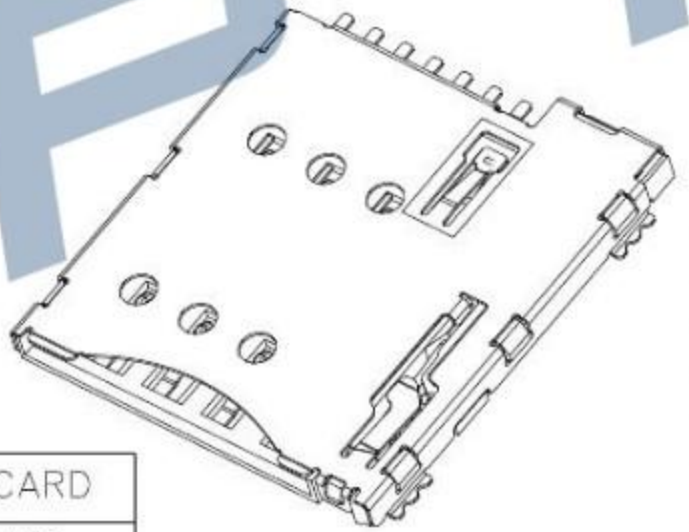
REV.	DESCRIPTION OF REVISIONS	APPR.	DRAW.	RELEASE	DATE
X1					
X2	Change Dim		Henry		2020.04.13



NO PATTERN AND VIA HOLE IN THIS AREA
 PAD AREA RECOMMENDED P.C.B LAYOUT COMPONENT SIDE(TOLERANCE ±0.05)

TECHNICAL CHARACTERISTICS
 1.General Characteristics
 Dimensions:17.20LX16.18WX1.35H mm
 Weight:Approx 0.50±0.2g
 Durability:3000 cycles min.
 2.Electrical Characteristics
 Contact resistance:50mΩ typical, 100mΩMax
 Insulation resistance:>1000MΩ/500V DC
 3.Solderability
 Vaporphase:215°C, 30sec.Max
 IR reflow:250°C,5sec.Max
 Manual soldering:370°C,3sec.Max
 4.Environmental Characteristics
 Operating temperature:-40°C~+85°C
 Operating humidity:10%~+95%RH

Micro SIM CARD	
Pin No.	NAME
C1	VCC
C2	RST
C3	CLK
C4	Reserved
C5	GND
C6	VPP
C7	I/O
C8	Reserved



ITEM	PART NAME	Q'TY	MATERIAL	FINISH
1	HOUSING	1	Hi-temp Thermoplastic	Black UL94V-0
2	DATA CONTACT	6	Copper Alloy	Contact area:Gold plated
3	SHELL	1	Stainless Steel	SMT area:Gold plated
4	COIL SPRING	1	SWP	
5	HEART CAM	1	Hi-temp Thermoplastic	Black UL94V-0
6	CAM PIN	1	Stainless Steel	

MUP[®] MUP INDUSTRIAL CO.,LTD.

NAME: MicroSIM Card Connector		DRAWN		DWG NO.:	
MODEL NO: MUP-C794-2A		CHECKED		DWG-MUP-C794-2A	
TYPE: Normally CLOSE MICRO-SIM PUSH/PUSH 6PIN 1.35H		APPROVAL		SHEET	
CUSTOMER DRAWING				1/1	
				REVISION	
				X2	

